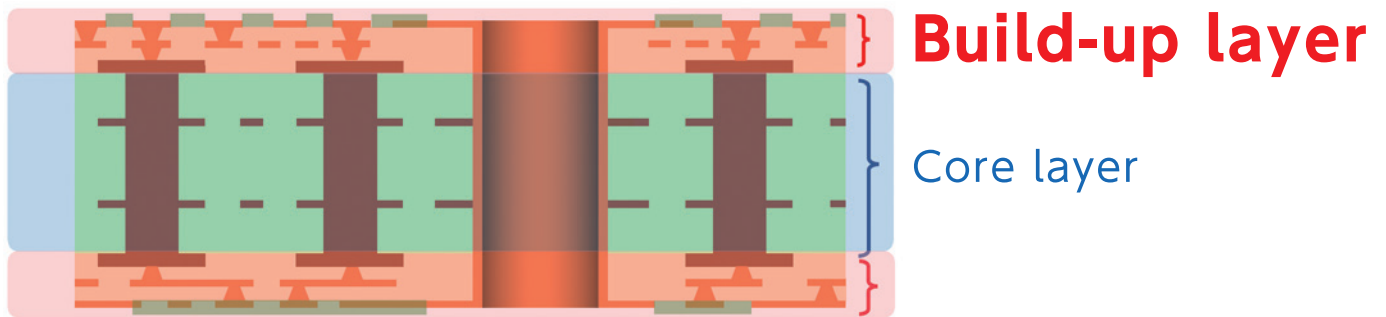


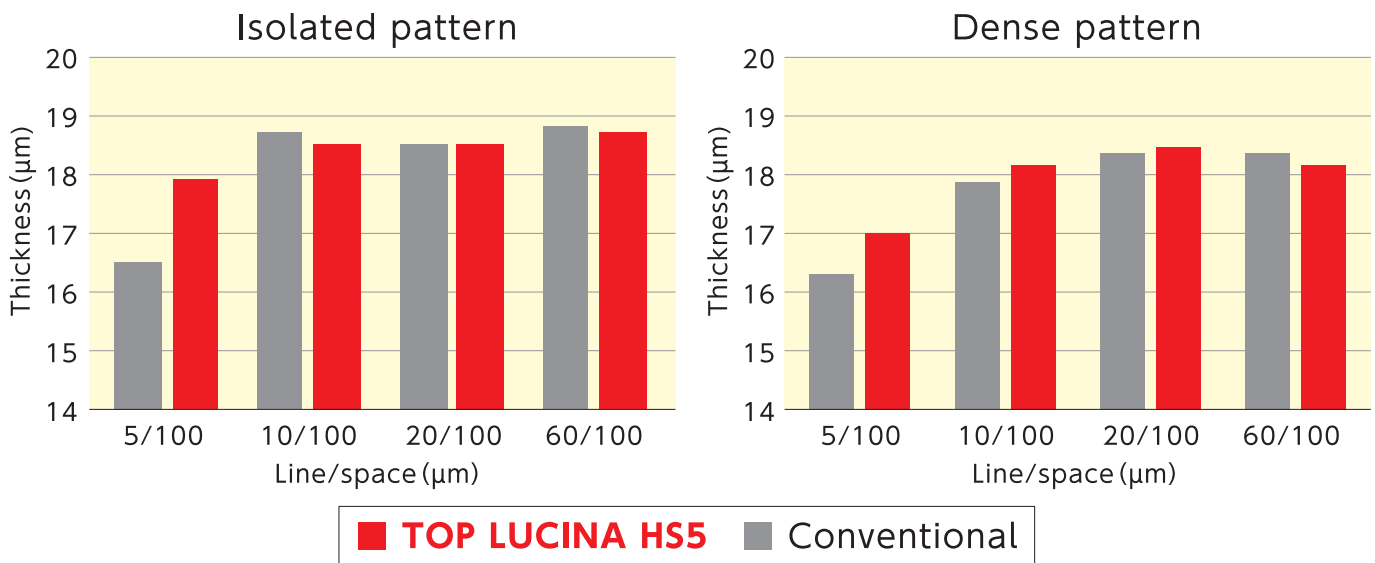
TOP LUCINA HS5

Additives for acid copper plating
for thickness uniformity

- For pattern plating to build-up layers to achieve thickness uniformity
- Can realize operation at 2 to 3 A/dm² current density
- Control dome-shape occurrence for stacked via



High thickness uniformity for ultra-fine patterning



Control dome-shape occurrence in overfilling

